

<(NAME) Project: (Workstream NAME)>

<Title: Product Specification Template>

<Version>.<Revision>.<Errata>

**Product Specification Template v1.4**

Effective XXXX, 2024

Author: <Primary>

Author: <Secondary. Delete if unnecessary>

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# License

PLEASE PICK EITHER THE OCP CLA OPTION OR THE OWF OPTION. ONLY ONE CAN BE USED. DELETE THE ONE NOT USED.

🗹 OPTION A: OCP CLA

🗹 OPTION B: Open Web Foundation (OWF) CLA

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## Acknowledgements

The Contributors of this Specification would like to acknowledge the following companies for their feedback:

List all companies or individuals who may have assisted you with the specification by providing feedback and suggestions but did not provide any IP.

# Compliance with OCP Tenets

Please describe how this Specification complies to the following OCP tenets. Compliance is required for at least four of the five tenets (Sustainability is a required tenet). The ideals behind open sourcing stipulate that everyone benefits when we share and work together. Any open source project is designed to promote sharing of design elements with peers and to help them understand and adopt those contributions. There is no purpose in sharing if all parties aren't aligned with that philosophy. The OCP Incubation Committee will look beyond the contribution for evidence that the contributor is aligned with this philosophy. The contributor actions, past and present, are evidence of alignment and conviction to all the tenets.

A full explanation of the OCP core tenets can be seen [here](https://146a55aca6f00848c565-a7635525d40ac1c70300198708936b4e.ssl.cf1.rackcdn.com/images/bf648bb75091907147e76846cad590f402660d2e.pdf).

## Openness

The measure of openness is the ability of a third party to build, modify, or personalize the device or platform from the contribution. OCP strives to achieve completely open platforms, inclusive of all programmable devices, firmware, software, and all mechanical and electrical design elements, including ancillary, external components or tools such as software utilities necessary to modify or use design contributions. Barriers to achieving this goal should be constantly addressed and actions taken to remove anything that prevents an open platform. Openness can also be demonstrated through collaboration and willingness to share, seek feedback, and accept changes to design and specification contributions under consideration. Ensure this contribution can be extended and enhanced by others.

## Efficiency

Continuous improvement has been a fundamental value of the industry. New contributions (and updates to existing contributions) shall be more efficient than existing or prior generation contributions. Efficiency can be measured in many ways - OpEx and CapEx reduction, performance, modularity, capacity, power or water consumption, raw materials, utilization, size or floorspace are some examples. The goal is to express efficiency with clear metrics, valued by end-users, when the contribution is proposed.

## Impact

OCP contributions should have a transformative impact on the industry. This impact can come from introducing new technology, time-to-market advantage of technology, and/or enabling technology through supply chains that deliver to many customers in many regions of the world. New technologies are impactful when such technology is enabled through a global supply channel. One example is the NIC 3.0 specification which achieved global impact by having over 12 companies author, adopt, and supply products that conformed to the specification. Another example is emerging and open security features that establish and verify trust of a product

## Scale

OCP contributions should be designed such that end products may be easily implemented and/or deployed, irrespective of quantity, with minimal intervention. Ensure all necessary tools, such as supporting documentation, etc., are included in the final contribution.

## **Sustainability**

OCP contributions must be sustainable. Submissions should maximize transparency of

environmental impacts of the contribution, with the aspiration of improvement over time.

Other focuses:

* Conscientious use of our natural resources (land, air, power, water and materials)
* Fostering positive societal impacts
* Minimizing Environmental Harm

Practically this can be realized in a base specification as high level design requirements, or architectural decisions, for example, that reflect this intent.

# Change Log

Note, refer to the OCP Contribution Versions, Revisions and Errata best practices documentation. Generally speaking, Versions and revisions are made to this document and logged here. Errata is a separate document such that the contribution specification document it refers to was not revised. Ex: Version 1, Errata E1

| **Date** | **Version #** | **Author** | **Description** |
| --- | --- | --- | --- |
| 03 JUL 23 | 1.1 | Bijan Nowroozi | Edited the goals in the overview for clarity |
| 08 AUG 23 | 1.2 | Bijan Nowroozi | Changed some of the sustainability text |
| 06 NOV 23 | 1.3 | Bijan Nowroozi | Terminology changes and edits for clarity |
| 30 SEP 24 | 1.4 | Bijan Nowroozi | Added usage note and compliance sections, updated numbering |
|  |  |  |  |
|  |  |  |  |
|  |  |  |  |

# Current Template Version:

OCP Modular Product Specification Template V1.4.0

# Scope

This document defines a Hardware Product Specification.

The Product Specification captures manufacturing requirements, building on the Design Specification. Typically even fewer companies will engage to create a single product specification, but the goal is to increase the total number of products that meet a Design Specification (derived from a Base Specification). The resulting Product Spec shall be contributed to OCP (via a Final Specification Agreement: FSA). A product typically goes through much effort for qualification and mass-production readiness beyond what specified in a typical design spec.

Product Specifications can be reused! I.e., assuming the base and design specifications allow, if one contributor creates a 110VAC design specification, another team could reuse and make an -48VDC product specification.

At Product(ization) Phase, even fewer companies may be involved to develop a specific final product for contribution to OCP. A Product may be submitted to OCP for “OCP Accepted™” or “OCP Inspired™” designation (with different levels of collateral such as a Design Package).

Please see the [presentation](https://146a55aca6f00848c565-a7635525d40ac1c70300198708936b4e.ssl.cf1.rackcdn.com/images/4d14a1280e13c7dcf17123678eedc7e56053de96.pdf) and [recording](https://www.youtube.com/watch?v=IKqGFyE0V9E) on the Modular Contribution Process from the OCP Global Summit 2022 for more information.

This document defines the technical details for one of the following types of specifications:

* Product Specification for an intended physical <hardware product type>
* modification of an existing product specification (state which existing spec is being modified)
  + either a complete revision update or
  + a minor version update
* a detailed specification for a <product type> with a product typically being available in 120 days of approval of this Spec.

Note: Any supplier seeking OCP recognition, for example OCP Accepted, for a hardware product, must be using a product spec that is 100% compliant with the preceding Base requirements, Design specification and these Product Specifications as described.

Examples are provided for reference only and can be found in the OCP Contribution Portal:

De-facto Standard -

Cooling Environments:

Server - [DC-MHS Modular Specs](https://www.opencompute.org/contributions?query=dcmhs&configure%5BfacetFilters%5D%5B0%5D=archived%3Afalse) \*

Network -

Rack -

Storage -

Cards -

Revision Update -

Version Update -

\* Note: Few Design Specifications were submitted prior to the final approved template.

# Overview

Describe your contribution or product. Include the problems it addresses. Explain its utility within the Open Compute Project ecosystem.

***INSTRUCTIONS FOR ALL FOLLOWING SECTIONS:***

* *Sections 6 – 17 are modeled on the required sections to document features and functions of the Hardware system, platform or card. If a section is not applicable to your contribution, you may delete any extra components.*
* *Where possible, please use the* [*OCP Terminology Guidelines for Inclusion and Openness*](https://www.opencompute.org/documents/ocp-terminology-guidelines-for-inclusion-and-openness)*.*
* *No NDA (Non-disclosure Agreement) or confidential material should be included in the document or charts. This will be an OPEN document.*

# Environmental / Regulatory Requirements

*Please describe any environmental regulations or requirements for any platform boards and full system, if applicable..*

*Note to author of this specification: This section can include the following but is not limited to the below items:*

* *UL/CE/NRTL/FCC/IEC/EN/etc Requirements*
* *RoHS/WEE directives, REACH regulations*
* *NEBS compliance requirements*
* *Operating temperature range*
* *Storage temperature range*
* *Transportation temperature range*
* *Shock and Vibration requirements*
* *Operating Altitude*

**

Example Outdoor Equipment Environmental Requirements

# Physical Specifications

*Please describe the physical requirements for your contribution. This may be the limitations of the physical envelope.*

*If this specification defines a chassis type system, be sure to include the description of the chassis and associated modules, midplane, backplanes etc….*

*Note to author of this specification: This section can include the following but is not limited to the below items:*

* *Block Diagrams*
* *Form Factor Requirements*
* *Figures & Illustrations*

**

Sample Block Diagram

## Mechanical

*Please describe any key mechanical requirements of your contribution.*

*Note to author of this specification: This section can include the following but is not limited to the below items:*

* *Chassis*
* *Single sled/double sled*

**

Dual-Band RRU Mechanical Requirements

# Electrical Requirements

*Please describe general electrical power requirements. Example: Power Input envelope +48VDC, 110VAC, peak/average power, etc…*

**

Dual-Band RRU Electrical Requirements

# Thermal Design Requirements

*Please describe the thermal design requirements for your contribution and any CFD and/or thermal models etc...*

*Note to author of this specification: Examples include:*

* *Cooling Media*
* *Flow Management*
* *Fan Controls*

**

Dual-Band RRU Thermal Requirements

# Interfaces

*Please describe the I/O System of the contribution, be sure to delineate the control and data planes. Block diagrams here.*

**

## Signal List

*Note to author of this specification: Examples only*

* *Power and Ground*
* *Synchronization/Clocks*
* *PCIe*
* *i2C/i3C*
* *GPIO*
* *USB 3.0*

## 10.2 Rear Side Power, I/O, Expansion Board and Midplane Subsystems

*Please describe any modular design implementation requirements of the contribution.*

*Note to author of this specification: This section can include the following but is not limited to the below items:*

* *​​Overview of Footprint and Population Options*
* *Rear Side Connectivity*
* *Midplane*
* *Expansion*
* *Fixed, redundant, modular, pluggable, adapter?*
* *Power, Grounding etc…*

**

Dual-Band RRU External Interface Requirements

# Onboard Power System

*Please describe the architecture of the power systems and requirements in your contribution.*

*Note to author of this specification: This section can include the following but is not limited to the below items:*

* *Voltage Regulation*
* *Power Management*
* *Input voltages*
* *Hot swap controller circuit*
* *Hard drive power*
* *Power Tree*
* *Power Policy*
* *Power Budget*
* *Platform Budget*
* *Capacitive Load*

# Prescribed Materials

*Please list any prescribed materials in your contribution. Specific components that are being referenced but not contributed.*

*Note to author of this specification: This section can include the following but is not limited to the below items:*

* *Disallowed components*

*Any specifically required components with no substitution (Ex: IC Intel JHL8540 or greater for Thunderbolt 4 compliance)*

# System Firmware

*Please document firmware function, and necessary features, licensing and distribution rights, explanation of ownership rights, system build utilities, test regime explanations, standards compliance, options for changing firmware configurations, and how firmware upgrades can be accomplished.*

*Note to author of this specification: This section can include the following but is not limited to the below items:*

* *BIOS Chip*
* *BIOS Feature Requirements*

# Hardware Management

*Please document the hardware management implementation of your contribution. Include Firmware (BIOS) optional Board Management Controller (BMC), Data Center Secure Control Modules (DC-SCM), etc.*

*Note to author of this specification: This section* ***should*** *include the following below items:*

* *Statement on whether the contribution supports out-of-band manageability.*
* *Statement on the modularity of the manageability architecture. (i.e. is an OCP management module used?)*

*Note to author of this specification: This section* ***can*** *include the following but is not limited to the below items:*

* *Architecture of out-of-band management*
  + *Dedicated or shared NIC*
  + *In which power state is the OOB management enabled*
* *A list of on-platform manageability interfaces:*
  + *Connections: I2C/I3C, SMBus, RMII,*
  + *Transport Protocol: MCTP, IPMI (KCS, BT, etc)*
  + *Commands constructs: PLDM …, IPMI, SPDM, CPER*
* *A list of components whose firmware which can updated programmatically*
  + *Which support failover/rollback mechanisms*
* *A list of diagnostic or management LEDs supported*
* *A list of minimum telemetry/sensors*
* *A list of minimum controls*
* *Whether conformance to OCP Profiles has been tested*
* *For Arm-based Servers, whether conformance to Arm Server Base Manageability Requirements Specification has been followed. If so, please also indicate the conformance level (e.g., M2)*

# Compliance

*This* ***mandatory*** *section is also applicable to create the checklist for the consumers of the specification to adhere to in order for them to declare it complies to the requirements. This applies to any implementations (OCP Marketplace or not) that declare compliance with this specification.*

*For a product specification, this declaration should refer to the base/design specifications, can include blanket statements if complies, and absolutely needs to list exceptions.*

*(Example Compliance Table Follows)*

| ***ITEM*** | ***REQUIREMENT*** | ***REFERENCE*** | ***COMPLIES*** |
| --- | --- | --- | --- |
| *1* | *If scalable HPM depth >372.5mm (from origin), additional Zone 2 KOZs shall be*  *implemented.* | *10.3.2 (multiple items)* | *Y* |
| *2* | *Optional: The device shall only clear the Timestamp Origin field to 000b in the Timestamp (Feature*  *Identifier 0Eh) on a main power cycle or NVM Subsystem Reset (e.g., NSSR). The device*  *shall not clear the Timestamp Origin field on a power cycle of only AUX power.* | *NVMe-OPT-4* | *N* |
| *3* | *Any supplier seeking OCP recognition for a hardware product based on this specification*  *shall be 100% compliant* | *4* | *Y* |

*All Products seeking OCP Accepted™ Product Recognition shall have source code and binary*

*blobs submitted for BMC, if applicable.*

*The BMC management source code shall be uploaded at:*

*https://github.com/opencomputeproject/Hardware-Management/[vendor\_name]/[product\_name]*

# Security

*Please briefly describe security functionality that* ***your specification requires and recommends\*****.*

*Include a “required by” date on recommendations. Omit what doesn’t apply and add whatever*

*is missing. Remember, the greater the detail in this specification, the less flexibility is allowed during design and product specification.*

* *For cryptography, key derivation, key agreement, and hashing, identify*

*o Required algorithms, modes, strengths, and usage*

*o Required compliance with national or international standards*

*o Acceptable sources of entropy*

*o Acceptable certifications of algorithm implementations*

*o Recommended certifications of cryptographic modules*

*o Recommended safeguards against cryptanalysis by quantum computers*

* *Required flow of Secure Boot starting from hardware root(s) of trust*
* *Required measurements from hardware reset through firmware*
* *Required attestation protocols*
* *Acceptable environments and processes for provisioning keys and device secrets*
* *Acceptable processes for identifying CVEs and distributing field updates to address them*
* *Acceptable Secure Boot and Attestation key lifecycle management (from generation through*
* *revocation)*
* *Recommended standards for software bills of materials*
* *Recommended firmware recovery mechanisms*

*\*Required = Required now*

*Acceptable = Required now and chosen from a list of acceptable alternatives*

*Recommended = Recommended now, but required by a specified future date*

*Please find guidance and examples in the OCP Security Project documents on* [*Secure Boot*](https://www.opencompute.org/documents/secure-boot-2-pdf)*,* [*Attestation of System Components*](https://www.opencompute.org/documents/attestation-v1-0-20201104-pdf)*,* [*Common Security Threats*](https://www.opencompute.org/documents/common-security-threats-notes-1-pdf)*, and the* [*CSIS document on Secure Firmware Development Best Practices*](https://www.opencompute.org/documents/csis-firmware-security-best-practices-position-paper-version-1-0-pdf)*.*

All products seeking OCP Inspired™ or OCP Accepted™ Product Recognition shall have a

completed Security Profile in the 2021 Supplier Requirements Checklist. Whether the answer is

a yes or no, the profile must be completed.

# Software Support (recommended)

*Please identify any software and/or tools used to validate the hardware design and include test and validation using virtual simulation, design decisions based upon digital models, or proof of manufacturability via 3-D tools.*

# Arm SystemReady (only for Arm-based Systems)

*Please document the requirement for this design to be compliant with the ARM SystemReady specifications.*

*For Server Sleds, Open Edge Sleds and Monolithic Servers, the certification of either SystemReady SR or LS certification is required.*

*For Storage and Networking, the certification of SystemReady SR, LS, ES, or IR is recommended.*

*For Systems that are SystemReady SR, ES or IR certified, SystemReady Security Interface Extension (SIE) certification is recommended.*

*More details on Arm SystemReady can be found at https://www.arm.com/architecture/system-architectures/systemready-certification-program.*

# References

1. “Title”, publication year, publication journal/conference/standard, volume, pages, link to publication if available

# Appendix A - Checklist for IC approval of this Specification (to be completed by contributor(s) of this Spec)

Complete all the checklist items in the table with links to the section where it is described in this spec or an external document .

| **Item** | **Status** | **Link to detailed explanation** |
| --- | --- | --- |
| Has this contribution been presented to an OCP Project group during a project call or engineering workshop? | Yes or No | If “No”, please state the reason. |
| Approval by Project Leads | Yes or No | If “No”, please state the reason. |
| Is this contribution entered into the OCP Contribution Portal? | Yes or No | If “No”, please state the reason. |
| Was it approved in the OCP Contribution Portal? | Yes or No | If “No”, please state the reason. |

# 

# Appendix B - Contribution Process FAQs

As a contributor to a hardware specification, here are some questions that often come up.

1. **What type of specification am I contributing to OCP?**
   1. **The base specification** for a de-facto standard (ex: interface type)
   2. The base specification for a product <product type> (product may be coming but within the next 1-2 years)
   3. Modification of an existing <type> specification (state which existing spec is being modified) resulting in a revised specification.
   4. **Design specification** (based on an existing base specification) with more refined design details (product coming in 12-15 months)
   5. A detailed **Product specification** for a <product type> for a very specific product being available in 3-6 months of approval of this Spec
   6. If none of the above, please contact OCP Staff for better direction.
2. **How do I know if what I am contributing will be accepted by OCP?**
   1. Before contributing any specifications, please contact either OCP Staff (Rob Coyle, Michael Schill) or the Project Lead for the Project that best represents your contribution. They will guide you as to what’s the best form for your contribution. Project List [here](https://www.opencompute.org/projects).
3. **What is the contribution process for my hardware spec?**
   1. Follow the flow for your spec type [here](https://docs.google.com/presentation/d/1PlXGLhCdgVEGWQ0hLYdAQEH5qCScwYij/edit#slide=id.g10e20dc1292_0_101).
4. **What if my spec is not developed yet and I want to collaborate with other companies?**
   1. Please contact either OCP Staff (Rob Coyle or Michael Schill) or the Project Lead for the Project that best represents your contribution. They will help you find other collaborators and help you with the contribution process for a multi-party contribution.
5. **I have a question about the Contribution License Agreement (CLA).** 
   1. Please contact OCP Staff and we can help you with questions.
6. **Do I need to have a product in order to make a contribution?**
   1. Please see Q1. Some types of contributions do not result in a product. Some examples are whitepapers, case studies, OCP Ready Assessment, etc.. Please work with the OCP Staff on the better direction on your specification type.